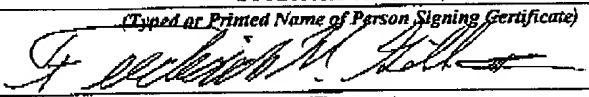


CERTIFICATE OF TRANSMISSION BY FACSIMILE (37 CFR 1.8)			Docket No. BUR920000016US1
Applicant(s): Divakaruni et al.			
Serial No. 09/718,850	Filing Date November 22, 2000	Examiner Samuel Gebremariam	Group Art Unit 2811
Invention: LOGIC STRUCTURE PROCESS AND APPLICATION FOR VERTICLE BIPOLAR TRANSISTOR			
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I hereby certify that this <u>Second Amendment Under 37 CFR 1.116</u> (Identify type of correspondence)			
is being facsimile transmitted to the United States Patent and Trademark Office (Fax. No. <u>703-872-9306</u>)			
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In re patent application of

Divakaruni et al.

Serial No.: 09/718,580

Group Art Unit: 2811

Filed: November 22, 2000

Examiner: Gebremariam, Samuel A.

For: LOGIC STRUCTURE PROCESS AND APPLICATION FOR VERTICLE
BIPOLAR TRANSISTORCommissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450**SECOND AMENDMENT UNDER 37 C.F.R. §1.116**

Sir:

In response to the Office Action mailed December 30, 2003, please amend the above-identified patent application as follows:

IN THE SPECIFICATION:

Please amend page 2, lines 2- 7 of the specification as follows:

It is advantageous in semiconductor manufacturing to simultaneously produce as many different types of devices on a chip ~~has~~ as possible. Such simultaneous production reduces the number of steps and the amount of material required to make the chip. This reduces the time and cost of producing semiconductor chips. Therefore, it is desirable to simultaneously form different types of transistors on a single chip.